

hi-tech division



pho**tronix**

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technical data

Layers	2 to 58, and 64 for samples
Maximum thickness	394 mil (10mm). 17.5 mm for samples
Materials	FR-4, Halogen-free, Rogers, BT, PTFE, PPO, PPE, Polyimide, Hybrid, ISOLA 370HR
Minimum width/spacing	Inner layer 3 mil/3 mil (Hoz). Outer layer 4 mil/4 mil (1oz)
Maximum copper thickness	6.0 oz (UL). 12 oz for samples
Minimum hole size	8 mil (0.2mm) mechanical drill. 3 mil (0.075mm) laser drill
Maximum panel size	1150 x 560 mm
Aspect ratio	18:1
Surface finishes	HASL, ENIG, ENEPIG, Immersion tin, OSP, Selective OSP, Immersion silver, Gold finger

Photronix is producing cutting edge products for the aerospace, medical and automotive industries, as well as highly complex commercial circuits. Utilising 6 Sigma Quality Control, and being the only Asian manufacturer to hold NADCAP aerospace approval, our quality is second to none. Advanced technologies such as Plated and Filled Via Holes (POFV), Embedded Components, Laser Drilling and HDI capability place us at the forefront of PCB manufacturing.

AS9100 ISO9001:2008 ISO14001:2004
NADCAP ISO/TS16949:2009



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